## 500V PNP HIGH PERFORMANCE TRANSISTOR IN SOT223

## Features

- $\mathrm{BV}_{\text {CEO }}>-500 \mathrm{~V}$
- $\mathrm{I}_{\mathrm{C}}=-150 \mathrm{~mA}$ High Continuous Current
- Iсм $=-500 \mathrm{~mA}$ Peak Pulse Current
- Totally Lead-Free \& Fully RoHS Compliant (Notes 1 \& 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- An Automotive-Compliant Part is Available Under Separate Datasheet (ZXTP01500BGQ)


## Mechanical Data

- Case: SOT223
- Case Material: Molded Plastic. "Green" Molding Compound. UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208③
- Weight: 0.112 grams (Approximate)

SOT223


Top View


Device Symbol


Top View Pin-Out

Ordering Information (Note 4)

| Part Number | Compliance | Marking | Reel Size (inches) | Tape Width (mm) | Quantity per Reel |
| :---: | :---: | :---: | :---: | :---: | :---: |
| ZXTP01500BGTC | Standard | ZXTP 01500B | 13 | 12 | 4,000 |

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) \& 2015/863/EU (RoHS 3) compliant.
2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain $<900 \mathrm{ppm}$ bromine, $<900 \mathrm{ppm}$ chlorine ( $<1500 \mathrm{ppm}$ total $\mathrm{Br}+\mathrm{Cl}$ ) and <1000ppm antimony compounds.
4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

## Marking Information



ZXTP01500B = Product Type Marking Code YWW = Date Code Marking
Y or $\bar{Y}=$ Last Digit of Year (ex: $9=2019)$ WW or WW = Week Code (01 to 53)

Absolute Maximum Ratings (@T $\mathrm{T}_{\mathrm{A}}=+25^{\circ} \mathrm{C}$, unless othervise specified.)

| Characteristic | Symbol | Value | Unit |
| :--- | :---: | :---: | :---: |
| Collector-Base Voltage | $\mathrm{V}_{\text {CBO }}$ | -500 | V |
| Collector-Emitter Voltage | $\mathrm{V}_{\text {CEO }}$ | -500 | V |
| Emitter-Base Voltage | $\mathrm{V}_{\text {EBO }}$ | -7 | V |
| Continuous Collector Current | $\mathrm{IC}_{C}$ | -150 | mA |
| Peak Pulse Current | $\mathrm{ICM}_{\text {CM }}$ | -500 | mA |

## Thermal Characteristics (@ $\mathrm{T}_{\mathrm{A}}=+22^{\circ} \mathrm{C}$, unless otherwise specified.)

| Characteristic |  | Symbol | Value | Unit |
| :---: | :---: | :---: | :---: | :---: |
| Power Dissipation | (Note 5) | PD | 2 | W |
|  | (Note 6) |  | 3 | W |
| Thermal Resistance, Junction to Ambient | (Note 5) | $\mathrm{R}_{\text {өJA }}$ | 62.5 | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |
|  | (Note 6) |  | 41.7 | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |
| Thermal Resistance, Junction to Leads | (Note 7) | $\mathrm{R}_{\text {өJL }}$ | 14.8 | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |
| Operating and Storage Temperature Range |  | $\mathrm{T}_{\mathrm{J}, \mathrm{T}}$ STG | -55 to +150 | ${ }^{\circ} \mathrm{C}$ |

## ESD Ratings (Note 8)

| Characteristic | Symbol | Value | Unit | JEDEC Class |
| :---: | :---: | :---: | :---: | :---: |
| Electrostatic Discharge - Human Body Model | ESD HBM | 4,000 | V | 3 A |
| Electrostatic Discharge - Machine Model | ESD MM | 400 | V | C |

Notes: $\quad 5$. For a device mounted with the collector lead on $25 \mathrm{~mm} \times 25 \mathrm{~mm} 2 \mathrm{oz}$ copper that is on a single-sided 1.6 mm FR-4 PCB; device is measured under still air conditions whilst operating in steady-state.
6. Same as note (5), except the device is mounted on $50 \mathrm{~mm} \times 50 \mathrm{~mm} 2 \mathrm{zz}$ copper.
7. Thermal resistance from junction to solder-point (at the end of the collector lead).
8. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

ZXTP01500BG

## Thermal Characteristics and Derating Information




Transient Thermal Impedance


Pulse Power Dissipation


Transient Thermal Impedance


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Electrical Characteristics ( $@ T_{A}=+25^{\circ} \mathrm{C}$, unless otherwise specified.)

| Characteristic | Symbol | Min | Typ | Max | Unit | Test Condition |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Collector-Base Breakdown Voltage | $\mathrm{BV}_{\text {CBO }}$ | -500 | - | - | V | $\mathrm{I}_{\mathrm{C}}=-100 \mu \mathrm{~A}$ |
| Collector-Emitter Breakdown Voltage (Note 9) | $B V_{\text {CEO }}$ | -500 | - | - | V | $\mathrm{IC}=-1 \mathrm{~mA}$ |
| Emitter-Base Breakdown Voltage | BVEBO | -7 | - | - | V | $\mathrm{I}_{\mathrm{E}}=-100 \mu \mathrm{~A}$ |
| Collector Cut-Off Current | $\mathrm{I}_{\text {CBO }}$ | - | - | -100 | nA | $\mathrm{V}_{\mathrm{CB}}=-500 \mathrm{~V}$ |
| Collector Cut-Off Current | Ices | - | - | -100 | nA | $\mathrm{V}_{\text {CE }}=-500 \mathrm{~V}$ |
| Emitter Cut-Off Current | $\mathrm{I}_{\text {EBO }}$ | - | - | -100 | nA | $\mathrm{V}_{\text {EB }}=-5.6 \mathrm{~V}$ |
| Collector-Emitter Saturation Voltage (Note 9) | $\mathrm{V}_{\text {CE(SAT) }}$ | - | - | -200 | mV | $\mathrm{IC}_{\mathrm{C}}=-20 \mathrm{~mA}, \mathrm{I}_{\mathrm{B}}=-2 \mathrm{~mA}$ |
|  |  | - | - | -500 |  | $\mathrm{I}_{\mathrm{C}}=-50 \mathrm{~mA}, \mathrm{I}_{\mathrm{B}}=-10 \mathrm{~mA}$ |
| Base-Emitter Saturation Voltage (Note 9) | $\mathrm{V}_{\text {BE(SAT }}$ | - | - | -900 | mV | $\mathrm{I}_{\mathrm{C}}=-50 \mathrm{~mA}, \mathrm{I}_{\mathrm{B}}=-10 \mathrm{~mA}$ |
| Base-Emitter Turn-On Voltage (Note 9) | $\mathrm{V}_{\mathrm{BE}}(\mathrm{ON})$ | - | - | -900 | mV | $\mathrm{I}_{\mathrm{C}}=-50 \mathrm{~mA}, \mathrm{~V}_{\mathrm{CE}}=-10 \mathrm{~V}$ |
| DC Current Gain (Note 9) | $h_{\text {FE }}$ | 100 | - | 300 | - | $\mathrm{I}_{\mathrm{C}}=-1 \mathrm{~mA}, \mathrm{~V}_{\text {CE }}=-10 \mathrm{~V}$ |
|  |  | 80 | - | 300 |  | $\mathrm{I}_{\mathrm{C}}=-50 \mathrm{~mA}, \mathrm{~V}_{\mathrm{CE}}=-10 \mathrm{~V}$ |
|  |  | - | 15 | - |  | $\mathrm{IC}=-100 \mathrm{~mA}, \mathrm{~V}_{\text {CE }}=-10 \mathrm{~V}$ |
| Current Gain-Bandwidth Product | $\mathrm{f}_{T}$ | 60 | - | - | MHz | $\begin{aligned} & V_{C E}=-20 \mathrm{~V}, \mathrm{I}_{\mathrm{C}}=-10 \mathrm{~mA} \\ & \mathrm{f}=50 \mathrm{MHz} \end{aligned}$ |
| Turn-On Time | ton | - | 110 | - | ns | $\mathrm{V}_{\mathrm{CC}}=-100 \mathrm{~V}, \mathrm{I}_{\mathrm{C}}=-50 \mathrm{~mA}$ |
| Turn-Off Time | toff | - | 1.5 | - | $\mu \mathrm{s}$ | $\mathrm{I}_{\mathrm{B} 1}=-5 \mathrm{~mA}, \mathrm{I}_{\mathrm{B} 2}=10 \mathrm{~mA}$ |
| Output Capacitance | Cobo | - | - | 8 | pF | $\mathrm{V}_{\mathrm{CB}}=-20 \mathrm{~V}, \mathrm{f}=1 \mathrm{MHz}$ |

Note: $\quad 9$. Measured under pulsed conditions. Pulse width $\leq 300 \mu$ s. Duty cycle $\leq 2 \%$.

## Typical Electrical Characteristics ( $\mathrm{CT}_{\mathrm{A}}=+25^{\circ} \mathrm{C}$, unless otherwise specified.)



## Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.


| SOT223 |  |  |  |
| :---: | :---: | :---: | :---: |
| Dim | Min | Max | Typ |
| A | 1.55 | 1.65 | 1.60 |
| A1 | 0.010 | 0.15 | 0.05 |
| b | 0.60 | 0.80 | 0.70 |
| b1 | 2.90 | 3.10 | 3.00 |
| C | 0.20 | 0.30 | 0.25 |
| D | 6.45 | 6.55 | 6.50 |
| E | 3.45 | 3.55 | 3.50 |
| E1 | 6.90 | 7.10 | 7.00 |
| e | - | - | 4.60 |
| e1 | - | - | 2.30 |
| L | 0.85 | 1.05 | 0.95 |
| $\mathbf{Q}$ | 0.84 | 0.94 | 0.89 |
| All Dimensions in $\mathbf{~ m m}$ |  |  |  |



## Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.
SOT223


| Dimensions | Value (in mm) |
| :---: | :---: |
| $\mathbf{C}$ | 2.30 |
| $\mathbf{C 1}$ | 6.40 |
| $\mathbf{X}$ | 1.20 |
| $\mathbf{X 1}$ | 3.30 |
| $\mathbf{Y}$ | 1.60 |
| $\mathbf{Y 1}$ | 1.60 |
| $\mathbf{Y 2}$ | 8.00 |

[^0]ZXTP01500BG

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[^0]:    Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.

